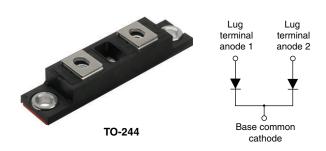


HEXFRED® Ultrafast Soft Recovery Diode, 167 A



PRODUCT SUMMARY					
I _F (maximum)	167 A				
V _R	600 V				
I _{F(DC)} at T _C	84 A at 100 °C				
Package	TO-244				
Circuit	Two diodes common cathode				

FEATURES

- Very low Q_{rr} and t_{rr}
- UL approved file E222165



- · Designed and qualified for industrial level
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

BENEFITS

- · Reduced RFI and EMI
- · Reduced snubbing

DESCRIPTION

HEXFRED® diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and dl_F/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Cathode to anode voltage	V_R		600	V	
Continuous forward current	ı	T _C = 25 °C	167		
Continuous forward current	I _F	T _C = 100 °C	84	Α	
Single pulse forward current	I _{FSM}	Limited by junction temperature	400		
Non-repetitive avalanche energy	E _{AS}	$L = 100 \mu H$, duty cycle limited by maximum T_J	330	μJ	
Maximum power dissipation P _D		T _C = 25 °C	310	W	
		T _C = 100 °C	132	VV	
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C	

ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	Ι _R = 100 μΑ		600	ı	-	
		I _F = 70 A		-	1.37	1.89	V
Maximum forward voltage V _{FM}	I _F = 140 A	See fig. 1	-	1.58	2.1		
		I _F = 70 A, T _J = 125 °C		-	1.29	1.54	
Maximum reverse leakage current	I _{RM}	T _J = 125 °C, V _R = 480 V	See fig. 2	-	1.2	4	mA
Junction capacitance	C _T	V _R = 200 V	See fig. 3	-	140	250	pF
Series inductance	L _S	From top of terminal hole to mounting plane		-	7.0	-	nH



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
		$I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	33	-		
Reverse recovery time (fig. 5)	t _{rr}	T _J = 25 °C	I _F = 70 A dI _F /dt = 200 A/μs V _R = 200 V	-	80	120	ns	
		T _J = 125 °C		-	140	220		
Peak recovery current (fig. 6)	I _{RRM}	T _J = 25 °C		-	8.5	15	A	
reak recovery current (lig. 0)		T _J = 125 °C		-	14	25		
Reverse recovery charge (fig. 7)	0	T _J = 25 °C		-	340	900	nC	
neverse recovery charge (lig. 7)	Q _{rr}	Q _{rr}	T _J = 125 °C		-	980	2300	iiC
Peak rate of recovery current (fig. 8) dl _{(rec)M} /dt	dl /dt	T _J = 25 °C		-	300	-	A/μs	
	ui _{(rec)M} /ut	T _J = 125 °C		-	220	-		

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER		SYMBOL	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature ra	nge		-55	-	150	°C
Thermal registance, junction to cook	per leg		T _J , T _{Stg}	- 0.38		
Thermal resistance, junction to case	per module		D	-	0.19	°C/W K/W
Typical thermal resistance, case to heatsink		R _{thCS}	R _{thJC}	0.10	-	
Weight			-	68	-	g
Weight			-	2.4	-	oz.
Mounting torque (1)			30 (3.4)	ı	40 (4.6)	
Mounting torque center hole			12 (1.4)	ı	18 (2.1)	N · m (lbf · in)
Terminal torque			30 (3.4)	-	40 (4.6)	(.2)
Vertical pull			-	- 80	80	lbf ⋅ in
2" lever pull			-	-	35	101 . 111

Note

⁽¹⁾ Mounting surface must be smooth, flat, free or burrs or other protrusions. Apply a thin even film or thermal grease to mounting surface. Gradually tighten each mounting bolt in 5 - 10 lbf · in steps until desired or maximum torque limits are reached

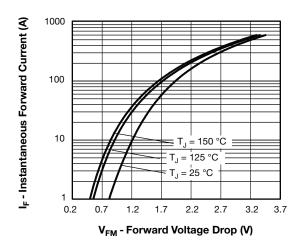


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

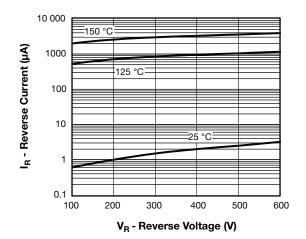


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

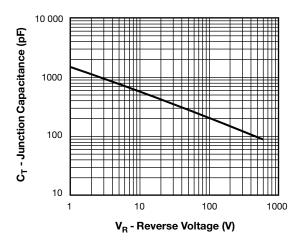


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

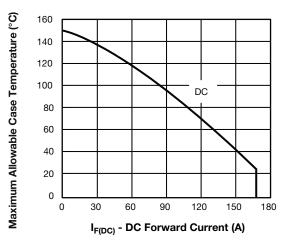


Fig. 4 - Maximum Allowable Case Temperature vs. DC Forward Current (Per Leg)

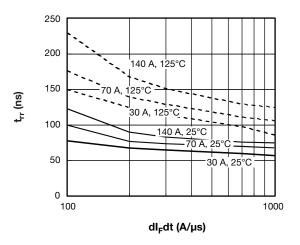


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

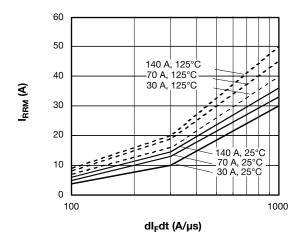


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

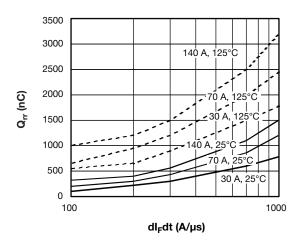


Fig. 7 - Typical Stored Charge vs. dl_F/dt (Per Leg)

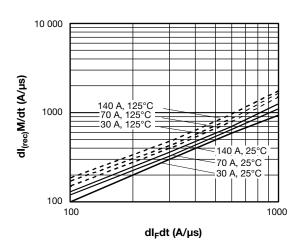


Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt (Per Leg)

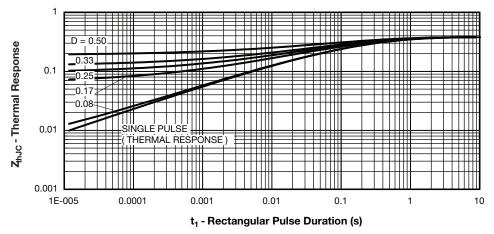


Fig. 9 - Maximum Thermal Impedance Z_{thJC} Characteristics

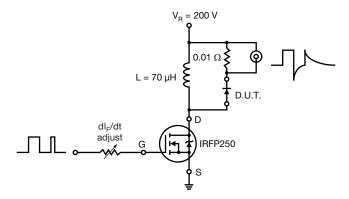
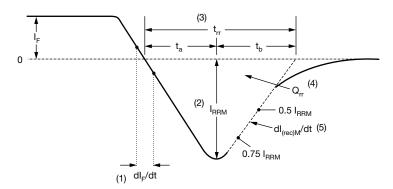


Fig. 10 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_{r}$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 11 - Reverse Recovery Waveform and Definitions



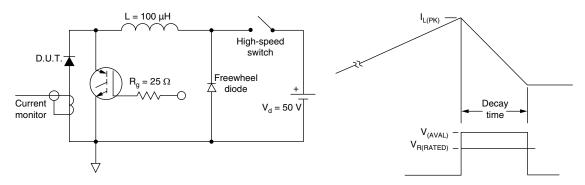
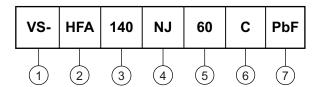


Fig. 12 - Avalanche Test Circuit and Waveforms

ORDERING INFORMATION TABLE

Device code



- 1 Vishay Semiconductors product
- 2 HEXFRED® family
- Average current rating
- **4** NJ = TO-244
- 5 Voltage rating (600 V)
- 6 C = Common cathode
- 7 Lead (Pb)-free

LINKS TO RELATED DOCUMENTS				
Dimensions <u>www.vishay.com/doc?95021</u>				



TO-244

DIMENSIONS in millimeters (inches)









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